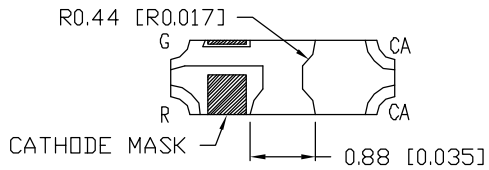
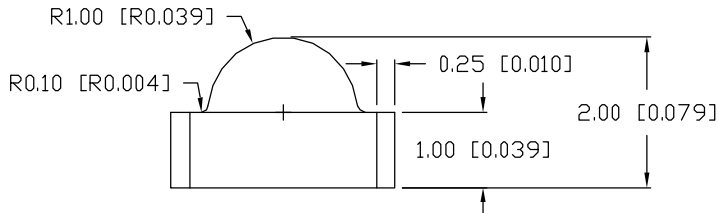
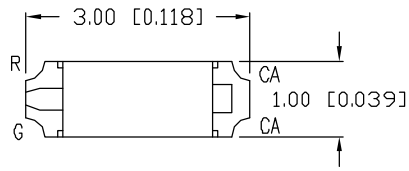


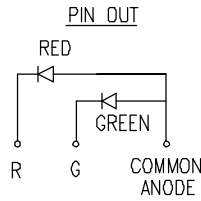
UNCONTROLLED DOCUMENT

PART NUMBER		REV.
SML-LXR851SISGC-TR		C
REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	E.C.N. #10865.	5.16.02
B	E.C.N. #10967.	9.07.04
C	E.C.N. #11148.	10.03.08

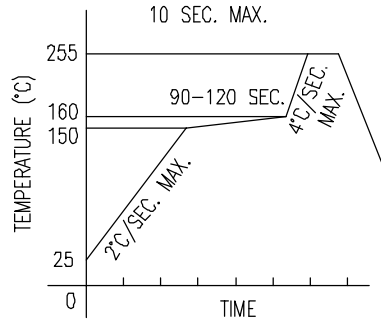


NOTES:

1. 2,000 PER REEL.



LEAD FREE REFLOW PROFILE



TOTAL TIME ABOVE 220°C IS 60 SECONDS MAX.

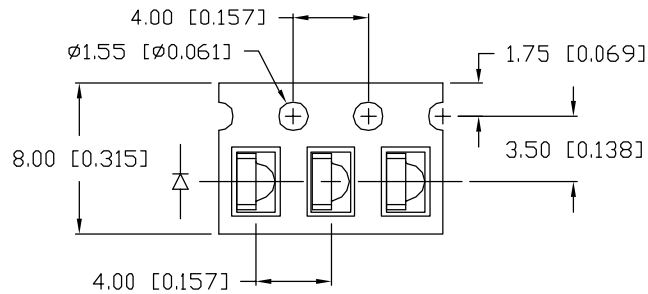
ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^\circ\text{C}$ $I_f=20\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		636 (RED)		nm	
		565 (GREEN)		nm	
FORWARD VOLTAGE (R/G)		2.0/2.1	2.4/2.4	V_f	
REVERSE VOLTAGE	5.0			V_r	$I_r=100\mu\text{A}$
AXIAL INTENSITY (R/G)		50/20		mcd	$I_f=20\text{mA}$
VIEWING ANGLE		120		2x theta	
EMITTED COLOR:	SUPER HIGH INTENSITY RED/SUPER GREEN				
EPOXY LENS FINISH:	WATER CLEAR				

LIMITS OF SAFE OPERATION AT 25°C PER CHIP

PARAMETER	COLORS	MAX	UNITS
PEAK FORWARD CURRENT*		160	mA
STEADY CURRENT	(R/G)	25/30	mA
POWER DISSIPATION	(R/G)	60/100	mW
DERATE FROM 25°C		-1.6	mW/°C
OPERATING TEMP.		-40 TO +85	°C
STORAGE TEMP.		-40 TO +90	°C

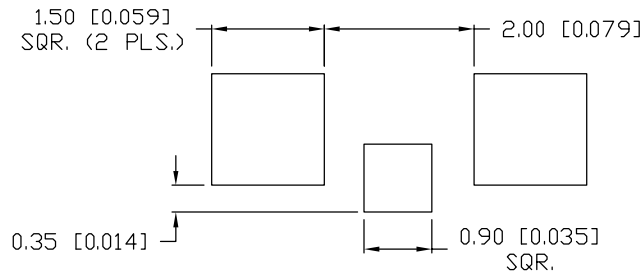
* $t < 10\mu\text{s}$



TAPE FEED DIRECTION

*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), XX=±0.5 (±0.020), XXX=±0.25 (±0.010), XXXX=±0.127 (±0.005).

RECOMMENDED SOLDER PAD LAYOUT



CAUTION: STATIC SENSITIVE DEVICE
FOLLOW PROPER E.S.D. HANDLING PROCEDURES
WHEN WORKING WITH THIS PART.

CAUTION: MOISTURE SENSITIVE DEVICE
PER JEDEC LEVEL 4 STANDARDS



UNCONTROLLED DOCUMENT

LEAD SIZE=±0.05 (0.002), LEAD LENGTH=±0.75 (±0.030). MIN= +DECIMAL PRECISION -0.00, MAX= +0.00 -DECIMAL PRECISION

REV.	PART NUMBER
C	SML-LXR851SISGC-TR
SURFACE MOUNT RIGHT ANGLE LED, 636nm RED/570nm GREEN BICOLOR LED, WATER CLEAR LENS.	

CONFIDENTIAL INFORMATION
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RELIABILITY NOTE
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

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		SCALE:	N/A